MULTI LAYER CERAMIC CAPACITORS - GML SERIES -

DESCRIPTION

- MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

- CCE GML series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R and X5R are used for this series product.

FEATURES

- Standard size with thin thickness.
- Small size with high capacitance.
- Capacitor with lead-free termination (pure Tin).

APPLICATIONS

- For LCD panels.
- For PCMCA cards.
- For IC packaging and modules.
- Any thickness concerned products.

ORDERING INFORMATION

GML	21	X5R	475	К	6R3	N	Т
SERIES	SIZE	DIELECTRIC	CAPACITANCE	TOLERANCE	VOLTAGE	TERMINATION	PACKAGING
GML - Low Profile	04 - 0402 (1005) 10 - 0603 (1608) 21 - 0805 (2012) 31 - 1206 (3216) 32 - 1210 (3225)	X7R X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point.	K: ±10% M: ±20%	Two significant digits followed by no. of zeros. And R is in place of decimal point.	N: Cu / Ni / Sn	T: 7″ reeled G: 13″ reeled
			eg.: 475 =47x105 =4,700,000 pF =4.7μF		6R3: 6.3 VDC 10: 10 VDC 16: 16 VDC 25: 25 VDC 50: 50 VDC		

GENERAL ELECTRICAL DATA

DIELECTRIC	X7R	X5R				
SIZE	0402, 0603, 0805, 1206, 1210					
CAPACITANCE RANGE*	0.1µF to 10µF	0.22µF to 47µF				
CAPACITANCE TOLERANCE**	K (±10%), M (±20%)					
RATED VOLTAGE	10V, 16V, 25V, 50V, 100V, 200V	6.3V, 10V, 16V, 25V				
OPERATING TEMPERATURE	-55 to +125°C	-55 to +85°C				
CAPACITANCE CHARACTERISTIC	±15%					
TERMINATION	Ni / Sn (lead-free termination)					

* Measured at 1.0±0.2Vrms, 1.0kHz±10%, 30~70% related humidity, 25°C ambient temperature for X7R, X5R.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement

DIMENSIONS

SIZE INCH (MM)	L (MM)	W (MM)	T (MM) SYMBO		MB (MM)	
0402 (1005)	1.00 ± 0.2	0.5 ± 0.2	0.30 ± 0.03	L	0.25 ± 0.10	
0603 (1608)	1.6 +15 / -0.10	0.8+ 0.15 / - 0.10	0.50 ± 0.10	н	0.40 ± 0.15	
0805 (2012)	2.00 ± 0.20	1.25±0.20	0.85 ± 0.10	т	0.50 ± 0.20	
1206	2 00 1 0 00	1 (0 , 0 00	0.85 ± 0.10	т		
(3216)	3.20 ± 0.20	1.60 ± 0.20	1.15 ± 0.15	J	0.60 ± 0.20	
-			0.85 ± 0.10	т		
1210 (3225)	3.20 ± 0.30	2.50±0.20	1.25 ± 0.10	U	0.75 ± 0.25	
			2.00 ± 0.20	к		

100: 100 VDC

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CAPACITANCE RANGE

- X7R Dielectric

	DIAELEC	TRIC		X7R										
	SIZE			08	05		1206				1210			
R	ATED VO	LTAGE	10 16 25 50		10	16	25	50	10	16	100	200		
	0.10 µF	104												U
	0.22 µF	224												
	0.33 µF	334												
	0.47 µF	474												
	0.68 µF	684												
出	0.82 µF	824												
RANGE	1.0 µF	105							т					
1 A.	1.5 µF	155												
CAP.	2.2 µF	225		Т										3.3
	3.3 µF	335												
	4.7 μF	475	Т						Т					
	6.8 µF	685												
	10 µF	106												
	22 µF	226							М					

- X5R Dielectric

_																				
	DIAELEC	TRIC		X5R																
	SIZE			0402			0603			08	05				1206				1210	
F	RATED VO	LTAGE	6.3	10	25	6.3	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
	0.22 µF	224			L		Н	Н												
	0.47 µF	474			L															
	1.0 µF	105	L				Н	Н												
	1.5 µF	155																		
RANGE	2.2 µF	225	L																	
		335																Т		
CAP	4.7 µF	475	L				Н		Т									Т		
10	6.8 µF	685																		
	10 µF	106				G			т	т	т	т	J	J/T		т		Т		Т
	22 µF	226	А																Т	
	47 μF	476																		

PACKAGING STYLE AND REEL SIZE

CIZE	THICKNES	S MASS	7" REEL				
SIZE	(MM) / S`	YMBOL	PAPER TAPE	PLASTIC TAPE			
0402 (1005)	0.22	F	10K				
0402 (1005)	0.33	L	15K				
0402 (1005)	0.7	А	10K				
0603 (1608)	0.50	G	4K	- b. (.).			
0603 (1608)	0.60	Н	4K				
0805 (2012)	0.95	Т	4K	-			
	0.95	Т	4K				
1206 (3216)	1.30	J	-	ЗК			
91/	1.65	М	_	2K			
61/	0.95	Т		ЗК			
1210 (3225)	1.35	U		ЗК			
01	2.00	K	_	1К			



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RELIABILITY TEST CONDITIONS AND REQUIREMENTS

NO.	ITEMS	TEST	T CON	IDITION		REQUI	REMENTS
1.	Visual and Mechanical			6/2/	- No remarkat - Dimensions		lividual specification sheet.
2.	Capacitance	- Test temp.: Room Temp			- Shall not exc	ceed the limits g	iven in the detailed spec.
3.		 Cap≤10µF, 1.0±0.2Vrms, Cap>10µF, 0.5±0.2Vrms, 			X7R / X5R:	RATED VOL.	D.F.
	Q/ D.F. (Dissipation	** Test condition: 0.5±0.2 GML10 X5R ≥475(10V) , 0				100V	≤5%
	Factor)					50V, 25V, 16V, 10V	≤10%
		*Before initial measureme 150°C for 1hr then set for		s II only): To apply de-aging at rs at room temp.		6.3V	≤5%
4.	Dielectric Strength	- To apply voltage: 250% - Duration: 1 to 5 sec. - Charge and discharge c			- No evidence	e of damage or f	lash over during test.
5.	Insulation Resistance	- Test temp.: Room Temp - To apply rated voltage f		120 sec.	≥10GΩ or Rx0	C ≥ 100Ω - F wh	ichever is smaller.
6.		With no electrical load.				12	
1		T.C.	OPER	ATING TEMPERATURE	-/ 7	T.C.	CAPACITANCE CHANGE
		X7R		-55~125°C at 25°C		X7R	Within ±15%
		X5R		-55~85°C at 25°C		X5R	Within ±15%
		- Before initial measureme To apply de-aging at 150' room temp. - Measurement voltage fo	№C for 1ł	hr then set for 24± 2 hrs at	56		
		0402		0603	0.0		
		Cap<1µF: 1V		Cap<1µF: 1V			
	Temperature Coefficient	Cap=1µF: 0.5V* 0402 X7R 224-16V: 0402 X7R 474-10V: 0402 X5R 475M6R3:	0.5V 0.5V	1µF≤Cap≤4.7µF: 0.5V 0603 X5R 106-10V: 0.5V			
		1µF<Сар<10µF: 0. **0402 X7R 105M6R3\	0.2V V: 0.2V	Cap>4.7µF: 0.2V	17		
		Сар≥10µF: 0.1V	v				
6		0005					
		0805		1206 / 1210			
Ο,		Cap<10µF: 1V Cap=10µF: 0.5V		Cap<10µF: 1V			
		0805 X7R 475/6.3V~ 0.5V		10µF <cap≤100µf: 0.5v<="" td=""><td></td><td></td><td></td></cap≤100µf:>			
		Cap>10µF: 0.2V	V	Cap>100µF: 0.2V 1206 X5R 107-6.3V: 0.2V			
7.	Adhesive Strength of Termination	- Pressurizing force: 5N (≤ - Test time: 10±1 sec.	≤ 0603) a	and 10N (>0603)	- No remarkat	ole damage or re	emoval of the terminations.
8.	Vibration Resistance	 Vibration frequency: 10- Total amplitude: 1.5mm Test time: 6 hrs. (Two hrs perpendicular directions.) Before initial measureme To apply de-aging at 150° room temp. Cap./DF(Q) Measureme 150°C for 1hr then set for 	s each in) ent (Clas °C for 11 ent to be	n three mutually ss II only): hr then set for 24± 2 hrs at made after de-aging at	- No remarkal - Cap change		neet initial spec.
9.	Solderability	- Solder temperature: 235 - Dipping time: 2±0.5 sec		_/((H	- 95% min. co	verage of all me	talized area.
10.	Bending Test	- The middle part of subs pressurized by means of t 1 mm per second until the the pressure shall be mair - Before initial measureme To apply de-aging at 150 room temp.	strate sha the press le deflect ntained f ent (Class l°C for 11	surizing rod at a rate of about tion becomes 1 mm and then for 5±1 sec.	(This ca capacita	: X7R/X5R: within pacitance chang ance underspeci	n ±12.5% Je means the change of fied flexure of substrate easured before the test.)

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RELIABILITY TEST CONDITIONS AND REQUIREMENTS

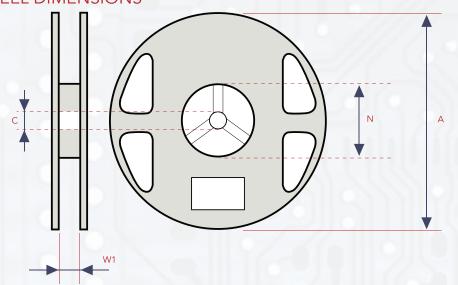
VO.	ITEMS		IEST CC	ONDITION	J	REQU	IREMENTS			
11.	Resistance to Soldering Heat	- Dipping time - Preheating: capacitor in a - Before initial at 150°C for 1 - Cap. / DF(Q)	120 to 150°C for eutectic solder. measurement (C hr then set for 24	1 minute be Class II only): 1±2 hrs at ro ent to be ma	de after de-aging a	 No remarkable damage. Cap change: X7R/X5R: within ±7.5% Q/D.F., I.R. and dielectric strength: To meet initial requirements. 25% max. leaching on each edge. 				
		- Conduct the	five cycles accor	ding to the t	emperatures and					
		time.								
		STE	.P TEMP.	(°C)	TIME (MIN)	000000				
		1	Min. operating		30±3	Na anna da bha da ma na				
12	2. Temperature	2	Room T		2~3	 No remarkable damage. Cap change: X7R/X5R: with 	in ±7.5%			
12.	Cycle	3	1 0	temp. +3/-0	30±3	- Q/D.F., I.R. and dielectric st requirements.	rength: To meet initial			
		4	Room T	[emp	2~3	requirements.				
		at 150°C for 1 - Cap. / DF(Q)	hr then set for 24	1±2 hrs at ro ent to be ma	de after de-aging					
	49	Test temp . /	0+2%			- No remarkable damage. - Cap change: X7R/X5R: with - Q/D.F. value: X7R/X5R:	in ±25%			
1		- Test temp.: 4 - Humidity: 90				RATED VOL.	D.F.			
13.	Humidity (Damp Heat)	- Test time: 50		lass II only).	To apply de-aging	100V	≤7.5%			
13.	Steady State	at 150°C for 1	hr then set for 24	4±2 hrs at ro	om temp.	25V, 16V	≤15%			
			/ I.R. Measurem hr then set for 24		de after de-aging	10V	≤20%			
						50V, 6.3V	≤30%			
						- I.R.: 1G Ω or RxC≥10 Ω -F v	vhichever is smaller.			
5			~95%RH 0+24/-0 hrs. age: Rated volta		No remarkable damage. *Cap change: X7R/X5R: with *Q/D.F. value: X7R/X5R:	in ±25%				
. (Humidity		hr then set for 24		To apply de-aging om temp .	RATED VOL.	D.F.			
14.	(Damp Heat)		/ I.R. Measurem hr then set for 24		de after de-aging	100V	≤7.5%			
	Load		In their set for Z	-2 ms at 10	om temp .	25V, 16V	≤15%			
		-				10V	≤20%			
						50V, 6.3V	≤30%			
						- I.R.: 500MΩ or RxC≥5 Ω-F v	vhichever is smaller.			
	C	- Test time: 10 - To apply volt	(7R: 125±3°C X 00+24/-0 hrs. age: 150% of rat ed voltage for be	ed voltage.	- No remarkable damage. - Cap change: X7R/X5R: with - Q/D.F. value: X7R/X5R:	in ±25%				
				CAPACITANE	RATED VOL.	D.F.				
C	High Temperature	SIZE	DIELECTRIC	RATED VOLTAG		100V	≤7.5%			
15.	Load	GML04	X5R	6.3V	C ≥ 1.0 µF	25V, 16V	≤15%			
1	(Endurance)	GML21	X5R X7R X6S	≤10V	C ≥ 10 µF	10V	≤20%			
		- Before initial	measurement (C	Class II only):	To apply de-aging	50V, 6.3V	≤30%			
/		at 150°C for 1 * - Cap. / DF(0	hr then set for 24 2) / I.R. Measurer et for 24±2 hrs at	1±2 hrs at ro ment to ©r c	- I.R.: $1G\Omega$ or $RxC \ge 10\Omega$ -F whichever is smaller.					



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MS LEVEL 1

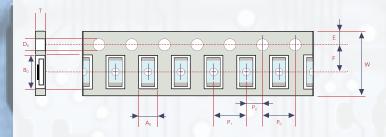
TAPE AND REEL DIMENSIONS

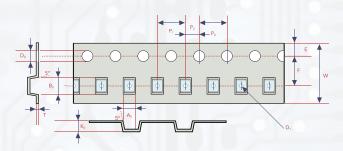


SIZE		0402, 0603, 0805, 1206, 1210	05, 1206, 1210				
REEL SIZE	7"	10″	13″				
С	13.0 ± 0.5	13.0 ± 0.5	13.0 ± 0.5				
W1	10.0 ±1.5	10.0 ± 1.5	10.0 ± 1.5				
A	178.0 ± 2.0	250.0 ± 2.0	330.0 ± 2.0				
N	60.0+1.0/-0	50 min	50 min				

- The dimension of paper tape

- The dimension of plastic tape

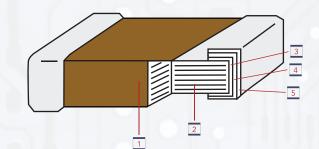




SIZE	0402	0603	0805	12	.06	12	10
THICKNESS		н	т	т	J	т	К
AO	0.70 ± 0.20	1.05 ± 0.30	1.50 ± 0.20	1.90 ± 0.50	<2.00	<3.05	<3.05
BO	1.20 ± 0.20	1.80 ± 0.30	2.30 ± 0.20	3.50 ± 0.50	<3.70	<3.80	<3.80
т	≤0.80	≤1.20	≤1.20	≤1.20	0.23 ± 0.1	0.23 ± 0.1	0.23 ± 0.1
K0	1.0	~.0	/	0.1	<2.00	<1.50	<2.50
W	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30	8.00 ± 0.30
PO	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10
10XP0	40.00 ± 0.10	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20	40.00 ± 0.20
P1	2.00 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	4.00 ± 0.10
P2	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05	2.00 ± 0.05
DO	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0	1.50 +0.1 / -0
D1			-	-	1.00 ± 0.10	1.00 ± 0.10	1.00 ± 0.10
E	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10	1.75 ± 0.10
F	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05	3.50 ± 0.05

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NO.	NA	X7R, X5R	
1	Cerami	BaTiO3 based	
2	Inner E	Ni	
3		Inner Layer	Cu
4	Termination	Middle Layer	Ni
5		Outer Layer	Sn (Matt)

STORAGE AND HANDLING CONDITIONS

(1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
(2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

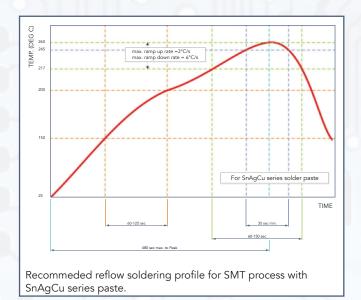
a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)

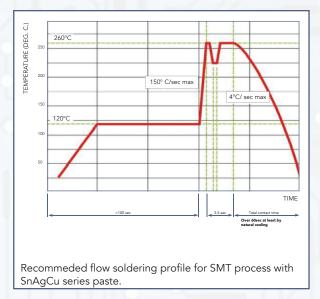
b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.

c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

RECOMMENDED SOLDERING CONDITIONS

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N2 within oven are recommended.







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